

**Dual P-Channel MOSFET** 

### **General Description**

WSD4280DN22 combines a P-Channel enhancement mode power MOSFET which is produced with high cell density and DMOS trench technology and a low forward voltage schottky diode. the tiny and thin outline saves PCB consumption.

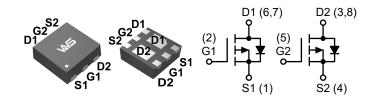
### **Applications**

- Bidirectional blocking switch;
- DC-DC conversion applications;
- Li-battery charging;

### **Product Summery**

BV <sub>DSS</sub>	R <sub>DSON</sub>	I <sub>D</sub>
-15V	47mΩ	-4.6A

### **DFN2X2-6S Pin Configuration**



## 5 Vgc`i hY`A UI]a i a `F Uh]b[gÁÁÇV₀nMáGÍ »ÔÁN} |^••ÁU c@\;ã ^Á⊳[c^åD

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-15	V
$V_{GS}$	Gate-Source Voltage	±8	V
I <sub>D</sub> @T <sub>c</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> = -4.5V <sup>1</sup>	-4.6	Α
I <sub>DM</sub>	300µS Pulsed Drain Current, (V <sub>GS</sub> =-4.5V)	-15	Α
$P_D$	Power Dissipation Derating above T <sub>A</sub> = 25°C (Note 2)	1.9	W
T <sub>STG</sub> ,T <sub>J</sub>	Storage Temperature Range	-55 to 150	$^{\circ}$
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	65	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	50	°C/W

Note1: Devices mounted on FR4 PCB with minima soldering pad;

Note2: For a single chip.



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# Electrical Characteristics $\hat{A}_{y}^{J}M\hat{A}\hat{A}_{y}^{J} = \hat{A}_{y}^{J} \hat{A}_{y}^{J} \hat{A}_{y}^{J} = \hat{A}_{y}^{J} \hat{A}_{y}^{J} = \hat{A}_{y}^{J} \hat{A}_{y}^{J} \hat{A}_{y}^{J} +$

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-15			V	
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =-1mA		-0.01		V/°C	
R <sub>DS(ON)</sub>		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-1A		47	61	mΩ	
	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-2.5V , I <sub>D</sub> =-1A		61	80		
		V <sub>GS</sub> =-1.8V , I <sub>D</sub> =-1A		90	150		
V <sub>GS(th)</sub>	Gate Threshold Voltage	\/ -\/     - 250\	-0.4	-0.62	-1.2	V	
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=-250uA$		3.13		mV/℃	
	Drain Source Lookage Current	$V_{DS}$ =-10V , $V_{GS}$ =0V , $T_J$ =25 $^{\circ}$ C			-1		
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS}$ =-10V , $V_{GS}$ =0V , $T_J$ =55 $^{\circ}$ C			-5	uA uA	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{\text{GS}} = \pm  12 \text{V}$ , $V_{\text{DS}} = 0 \text{V}$			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =-5V , I <sub>D</sub> =-1A		10		S	
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		2		Ω	
Qg	Total Gate Charge (-4.5V)	V <sub>DS</sub> =-10V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-4.6A		9.5			
$Q_{gs}$	Gate-Source Charge			1.4		nC	
$Q_gd$	Gate-Drain Charge			2.3			
T <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD}$ =-10V , $V_{GS}$ =-4.5V , $R_{G}$ =1 $\Omega$ $I_{D}$ =-3.9A,		15			
Tr	Rise Time			16		ns	
$T_{d(off)}$	Turn-Off Delay Time			30			
T <sub>f</sub>	Fall Time			10			
Ciss	Input Capacitance			781			
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =-10V , V <sub>GS</sub> =0V , f=1MHz		98		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			96			

#### Note:

<sup>1.</sup> The data tested by surface mounted on a 1 inch $^2$  FR-4 board with 2OZ copper, t $\leq$ 10sec.

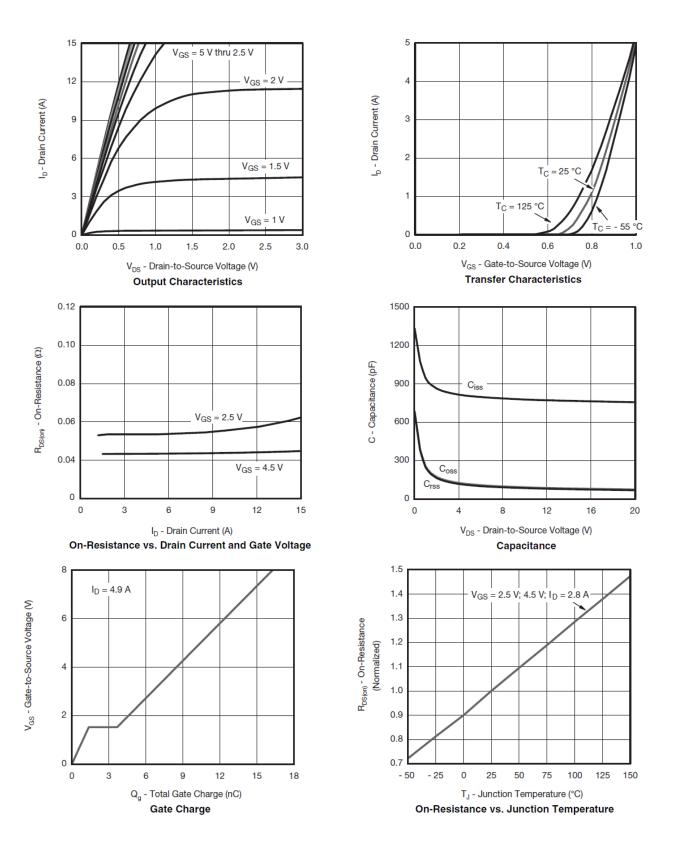
<sup>2.</sup>The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%

<sup>3.</sup> The power dissipation is limited by 150 ℃ junction temperature

<sup>4.</sup>The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

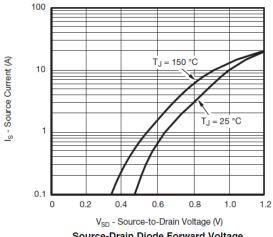


## **Typical Characteristics**

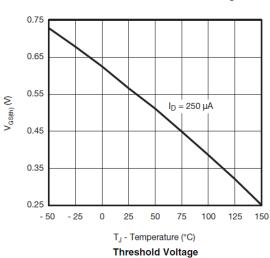




## **Typical Characteristics (Cont.)**

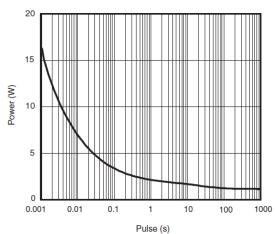


Source-Drain Diode Forward Voltage

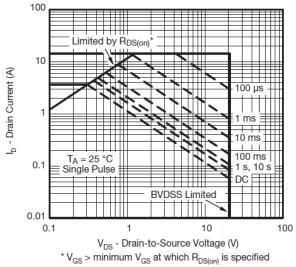


0.12 0.12 R<sub>DS(on)</sub> - On-Resistance (Ω)  $I_D = 3.8 \text{ A}; T_J = 25 \,^{\circ}\text{C}$ 0.10 I<sub>D</sub> = 3.8 A; T<sub>J</sub> = 125 °C 0.08 0.06 0.04 0.00 V<sub>GS</sub> - Gate-to-Source Voltage (V)

On-Resistance vs. Gate-to-Source Voltage

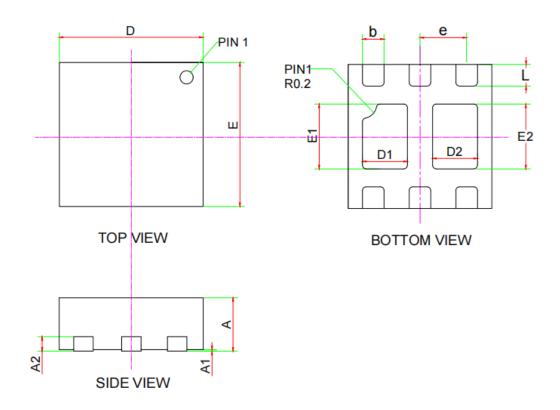


Single Pulse Power, Junction-to-Ambient





## **Packaging information**



SYMBOL	MIN	NOM	MAX	
Α	0.70	0.75	0.80	
A1	0.00	0.02	0.05	
A2	0.18	0.20	0.25	
D	1.95	2.00	2.05	
E	1.95	2.00	2.05	
b	0.25	0.30	0.35	
L	0.25	0.30	0.35	
D1	0.475	0.625	0.725	
E1	0.75	0.90	1.00	
D2	0.475	0.625	0.725	
E2	0.75	0.90	1.00	
R	0.20 REF			
е	0.65 BSC			



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